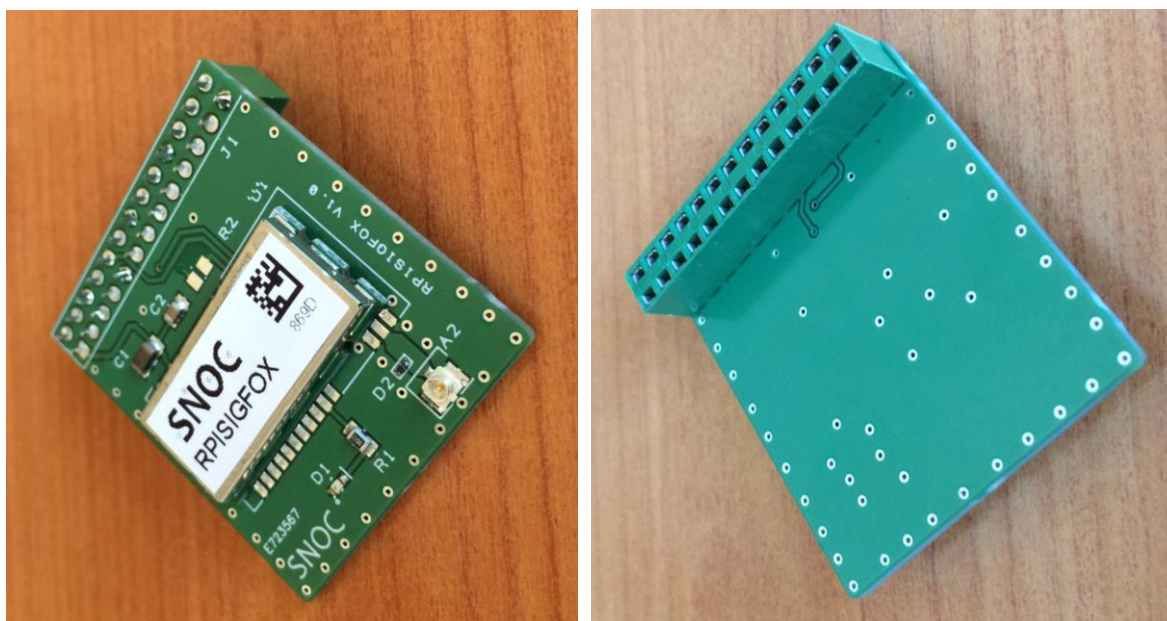


## Fiche assemblage produit

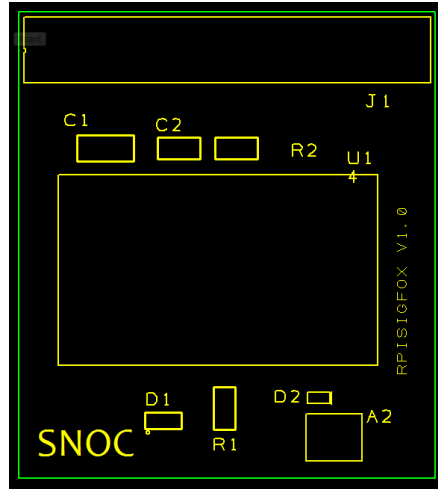
Référence: **PF0000350**



### Caractéristiques du PCB:

- Number of layers 2
- PCB width (X) 34.00 mm
- PCB height (Y) 38.00 mm
- Outer layer trackwidth (OL - TW) 0.150 mm
- Outer layer isolation distance (OL - TT - TP - PP) 0.150 mm
- Outer layer annular ring (OAR) 0.125 mm
- Top soldermask Vert
- Bottom soldermask Vert
- Top legend Blanc
- Board thickness 1.55 mm
- Base material FR4

**Implantation des composants :**



Note : Le connecteur J1 est à monter sous le PCB

**Nomenclature:**

Ref	Component	Value	Qty	Package	Manufacturer
C2	12061A100JATDA	10uF/6V3	1	SM1206	
C1	C0805C104K5RAC	100nF	1	SM0805	
D1	chipléd 0603 verte		1	0603	
D2	ESD9R3.3T5G		1	USER	On Semiconductor/ESD9R3.3T5G
R1	R 0.1W SMTF 220	220	1	SM0805	
R2	R 0.1W SMTF 220	220/NC	1	SM0805	
J1	13x2 HEADER 2.54		1	DIL	
U1	TD1207		1	USER	TelecomDesign
A2	UFL Conn		1	USER	HIROSE (HRS) /U.FL-R-SMT-1 (10)